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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, LCD, POR, PWM, WDT
Number of I/O	66
Program Memory Size	8KB (4K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 12x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf8393-i-pt

PIC18F6393/6493/8393/8493

64/80-Pin High-Performance, Flash Microcontrollers with LCD Driver, 12-Bit ADC and nanoWatt Technology

LCD Driver Module Features:

- Direct Driving of LCD Panel
- Up to 192 Pixels: Software-Selectable
- Programmable LCD Timing module:
  - Multiple LCD timing sources available
  - Up to four commons: Static, 1/2, 1/3 or 1/4 multiplex
  - Static, 1/2 or 1/3 bias configuration
- Can Drive LCD Panel while in Sleep mode for Low-Power Operation

Power-Managed Modes:

- Run: CPU On, Peripherals On
- Idle: CPU Off, Peripherals On
- Sleep: CPU Off, Peripherals Off
- Ultra Low 50 nA Input Leakage
- Run mode Current Down to 14 μA Typical
- Idle mode Currents Down to 2.3 μA Typical
- Sleep mode Currents Down to 0.1 μA Typical
- Timer1 Oscillator: 1.0 μA, 32 kHz, 2V Typical
- Watchdog Timer: 1.7 μA Typical
- Two-Speed Oscillator Start-up

Flexible Oscillator Structure:

- Four Crystal modes, up to 40 MHz
- 4x Phase Lock Loop (available for crystal and internal oscillators)
- Two External RC modes, up to 4 MHz
- Two External Clock modes, up to 40 MHz
- Internal Oscillator Block:
  - Fast wake from Sleep and Idle, 1 μs typical
  - Eight selectable frequencies, from 31 kHz to 8 MHz
  - Provides a complete range of clock speeds from 31 kHz to 32 MHz when used with PLL
  - User-tunable to compensate for frequency drift
- Secondary Oscillator Using Timer1 at 32 kHz
- Fail-Safe Clock Monitor:
  - Allows for safe shutdown if peripheral clock stops

Peripheral Highlights:

- 12-Bit, up to 12-Channel Analog-to-Digital (A/D) Converter module:
  - Auto-acquisition capability
  - Conversion available during Sleep
- High-Current Sink/Source 25 mA/25 mA
- Four External Interrupts
- Four Input Change Interrupts
- Four 8-Bit/16-Bit Timer/Counter modules
- Real-Time Clock (RTC) Software module:
  - Configurable 24-hour clock, calendar, automatic 100-year or 12,800-year, day-of-week calculator
  - Uses Timer1
- Up to Two Capture/Compare/PWM (CCP) modules
- Master Synchronous Serial Port (MSSP) module Supporting Three-Wire SPI (all four modes) and I^2C™ Master and Slave modes
- Addressable USART module:
  - Supports RS-485 and RS-232
- Enhanced Addressable USART module:
  - Supports RS-485, RS-232 and LIN/J2602
  - Auto-wake-up on Start bit
  - Auto-Baud Detect
- Dual Analog Comparators with Input Multiplexing
- Programmable 16-Level High/Low-Voltage Detection (HLVD) module:
  - Supports interrupt on High/Low-Voltage Detection

Special Microcontroller Features:

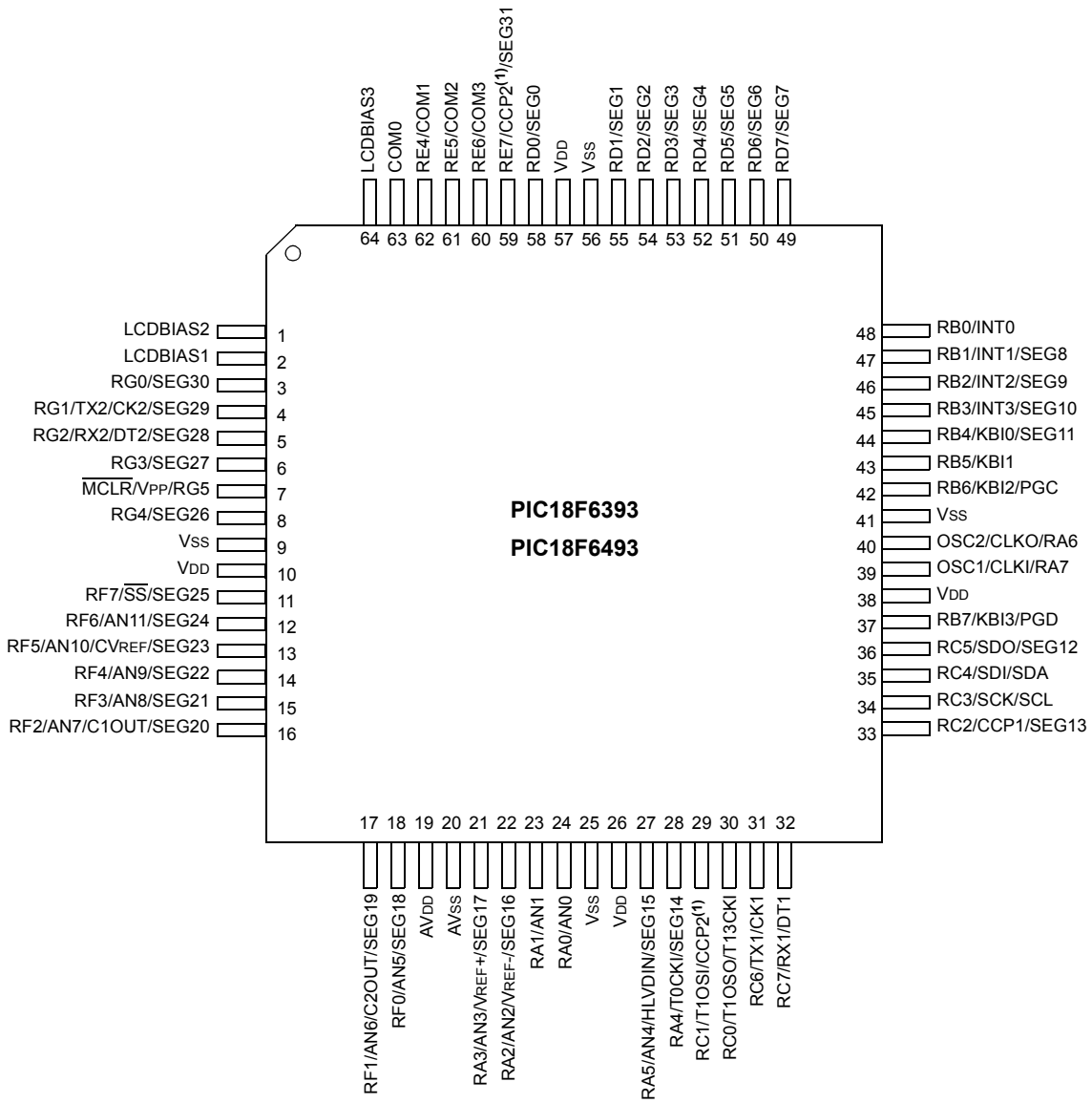
- C Compiler Optimized Architecture:
  - Optional extended instruction set designed to optimize re-entrant code
- 1000 Erase/Write Cycle Flash Program Memory, Typical
- Flash Retention: 100 Years Typical
- Priority Levels for Interrupts
- 8 x 8 Single-Cycle Hardware Multiplier
- Extended Watchdog Timer (WDT):
  - Programmable period from 4 ms to 132s
  - 2% stability over V_{DD} and temperature
- In-Circuit Serial Programming™ (ICSP™) via Two Pins
- In-Circuit Debug (ICD) via Two Pins
- Wide Operating Voltage Range: 2.0V to 5.5V
- Programmable Brown-out Reset (BOR) with Software Enable Option

Note: This document is supplemented by the *"PIC18F6390/6490/8390/8490 Data Sheet"* (DS39629). See **Section 1.0 "Device Overview"**.

Device	Program Memory		Data Memory	I/O	LCD (pixel)	12-Bit A/D (channels)	CCP (PWM)	MSSP		EUSART/ AUSART	Comparators	Timers 8/16-Bit
	Flash (bytes)	# Single-Word Instructions	SRAM (bytes)					SPI	Master I^2C™			
PIC18F6393	8K	4096	768	50	128	12	2	Y	Y	1/1	2	1/3
PIC18F6493	16K	8192	768	50	128	12	2	Y	Y	1/1	2	1/3
PIC18F8393	8K	4096	768	66	192	12	2	Y	Y	1/1	2	1/3
PIC18F8493	16K	8192	768	66	192	12	2	Y	Y	1/1	2	1/3

Pin Diagrams

64-Pin TQFP



Note 1: RE7 is the alternate pin for CCP2 multiplexing.

1.0 DEVICE OVERVIEW

This document contains device-specific information for the following devices:

- PIC18F6393
- PIC18F6493
- PIC18F8393
- PIC18F8493

Note: This data sheet documents only the devices' features and specifications that are in addition to the features and specifications of the PIC18F6390/6490/8390/8490 devices. For information on the features and specifications shared by the PIC18F6393/6493/8393/8493 and PIC18F6390/6490/8390/8490 devices, see the *"*PIC18F6390/6490/8390/8490 *Data Sheet"* (DS39629).

This family offers the advantages of all PIC18 microcontrollers – namely, high computational performance at an economical price. In addition to these features, the PIC18F6393/6493/8393/8493 family introduces design enhancements that make these microcontrollers a logical choice for many high-performance, power-sensitive applications.

1.1 Special Features

- **12-Bit A/D Converter:** This module incorporates programmable acquisition time, allowing for a channel to be selected and a conversion to be initiated without waiting for a sampling period and thus, reduces code overhead.

1.2 Details on Individual Family Members

Devices in the PIC18F6393/6493/8393/8493 family are available in 64-pin (PIC18F6X93) and 80-pin (PIC18F8X93) packages. Block diagrams for the two groups are shown in Figure 1-1 and Figure 1-2, respectively.

The devices are differentiated from each other in the following ways:

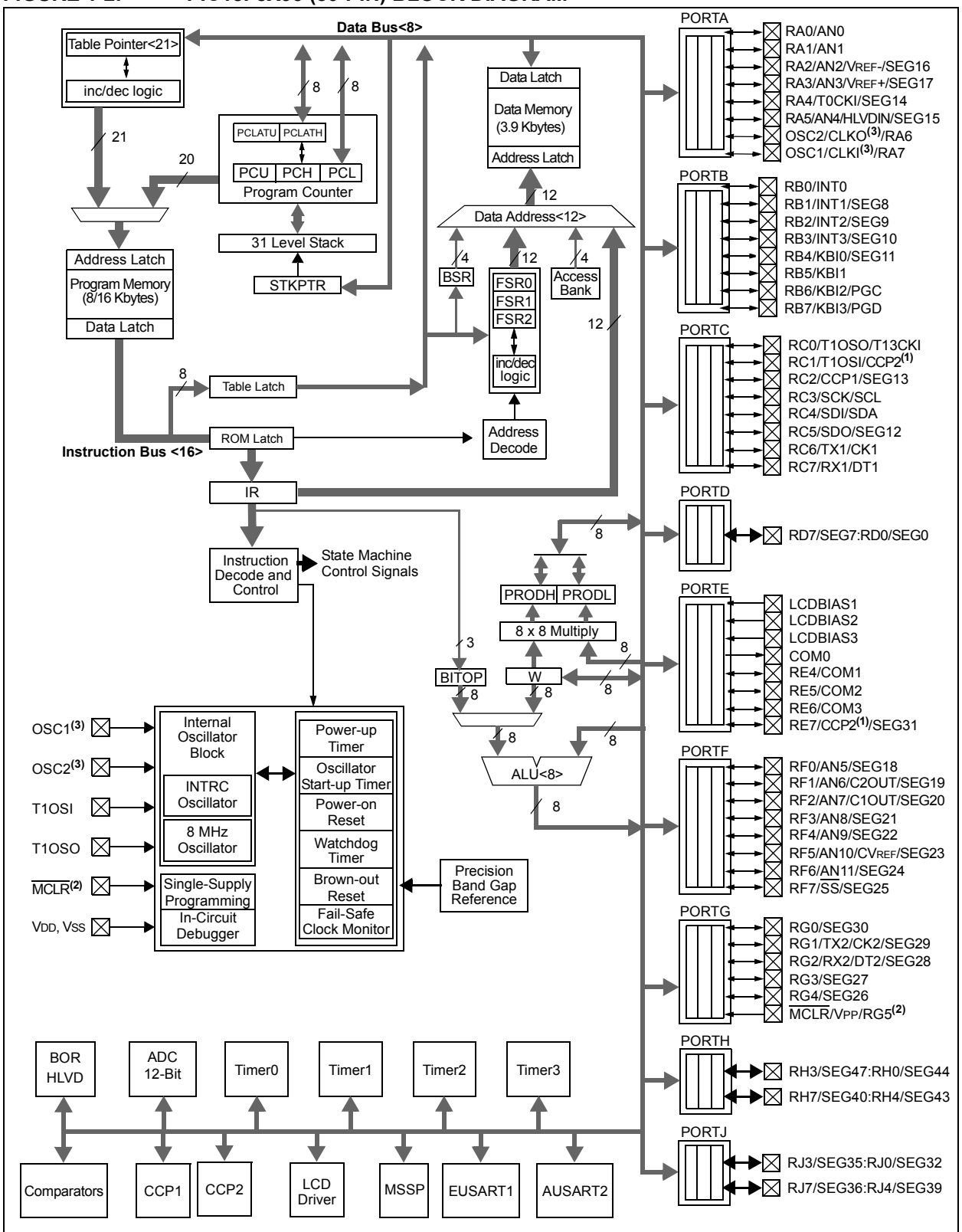
- I/O Ports:
  - 64-pin devices – 7 bidirectional ports
  - 80-pin devices – 9 bidirectional ports
- LCD Pixels:
  - 64-pin devices – 128 (32 SEGs x 4 COMs) pixels can be driven
  - 80-pin devices – 192 (48 SEGs x 4 COMs) pixels can be driven
- Flash Program Memory:
  - PIC18FX393 devices – 8 Kbytes
  - PIC18FX493 devices – 16 Kbytes

All other features for devices in this family are identical. These are summarized in Table 1-1.

The pinouts for all devices are listed in Table 1-2 and Table 1-3.

Like all Microchip PIC18 devices, members of the PIC18F6393/6493/8393/8493 family are available as both standard and low-voltage devices. Standard devices with Flash memory, designated with an "F" in the part number (such as PIC18F6393), accommodate an operating V_{DD} range of 4.2V to 5.5V. Low-voltage parts, designated by "LF" (such as PIC18LF6490), function over an extended V_{DD} range of 2.0V to 5.5V.

FIGURE 1-2: PIC18F8X93 (80-PIN) BLOCK DIAGRAM



Note 1: CCP2 is multiplexed with RC1 when Configuration bit, CCP2MX, is set and RE7 when CCP2MX is not set.

2: RG5 is only available when $\overline{\text{MCLR}}$ functionality is disabled.

3: OSC1/CLKI and OSC2/CLKO are only available in select oscillator modes and when these pins are not being used as digital I/O. For additional information, see **Section 2.0 "Oscillator Configurations"** of the "PIC18F6390/6490/8390/8490 *Data Sheet"* (DS39629).

TABLE 1-2: PIC18F6X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTA is a bidirectional I/O port.
RA0/AN0	24			
RA0		I/O	TTL	Digital I/O.
AN0		I	Analog	Analog Input 0.
RA1/AN1	23			
RA1		I/O	TTL	Digital I/O.
AN1		I	Analog	Analog Input 1.
RA2/AN2/VREF-/SEG16	22			
RA2		I/O	TTL	Digital I/O.
AN2		I	Analog	Analog Input 2.
VREF-		I	Analog	A/D reference voltage (Low) input.
SEG16		O	Analog	SEG16 output for LCD.
RA3/AN3/VREF+/SEG17	21			
RA3		I/O	TTL	Digital I/O.
AN3		I	Analog	Analog Input 3.
VREF+		I	Analog	A/D reference voltage (High) input.
SEG17		O	Analog	SEG17 output for LCD.
RA4/T0CKI/SEG14	28			
RA4		I/O	ST	Digital I/O.
T0CKI		I	ST	Timer0 external clock input.
SEG14		O	Analog	SEG14 output for LCD.
RA5/AN4/HLVDIN/SEG15	27			
RA5		I/O	TTL	Digital I/O.
AN4		I	Analog	Analog Input 4.
HLVDIN		I	Analog	Low-Voltage Detect input.
SEG15		O	Analog	SEG15 output for LCD.
RA6				See the OSC2/CLKO/RA6 pin.
RA7				See the OSC1/CLKI/RA7 pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C = ST with I^2C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-2: PIC18F6X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTD is a bidirectional I/O port.
RD0/SEG0	58			
RD0		I/O	ST	Digital I/O.
SEG0		O	Analog	SEG0 output for LCD.
RD1/SEG1	55			
RD1		I/O	ST	Digital I/O.
SEG1		O	Analog	SEG1 output for LCD.
RD2/SEG2	54			
RD2		I/O	ST	Digital I/O.
SEG2		O	Analog	SEG2 output for LCD.
RD3/SEG3	53			
RD3		I/O	ST	Digital I/O.
SEG3		O	Analog	SEG3 output for LCD.
RD4/SEG4	52			
RD4		I/O	ST	Digital I/O.
SEG4		O	Analog	SEG4 output for LCD.
RD5/SEG5	51			
RD5		I/O	ST	Digital I/O.
SEG5		O	Analog	SEG5 output for LCD.
RD6/SEG6	50			
RD6		I/O	ST	Digital I/O.
SEG6		O	Analog	SEG6 output for LCD.
RD7/SEG7	49			
RD7		I/O	ST	Digital I/O.
SEG7		O	Analog	SEG7 output for LCD.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C = ST with I^2C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-3: PIC18F8X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTD is a bidirectional I/O port.
RD0/SEG0	72			
RD0		I/O	ST	Digital I/O.
SEG0		O	Analog	SEG0 output for LCD.
RD1/SEG1	69			
RD1		I/O	ST	Digital I/O.
SEG1		O	Analog	SEG1 output for LCD.
RD2/SEG2	68			
RD2		I/O	ST	Digital I/O.
SEG2		O	Analog	SEG2 output for LCD.
RD3/SEG3	67			
RD3		I/O	ST	Digital I/O.
SEG3		O	Analog	SEG3 output for LCD.
RD4/SEG4	66			
RD4		I/O	ST	Digital I/O.
SEG4		O	Analog	SEG4 output for LCD.
RD5/SEG5	65			
RD5		I/O	ST	Digital I/O.
SEG5		O	Analog	SEG5 output for LCD.
RD6/SEG6	64			
RD6		I/O	ST	Digital I/O.
SEG6		O	Analog	SEG6 output for LCD.
RD7/SEG7	63			
RD7		I/O	ST	Digital I/O.
SEG7		O	Analog	SEG7 output for LCD.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C = ST with I^2C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-3: PIC18F8X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTE is a bidirectional I/O port.
LCDBIAS1	4			
LCDBIAS1		I	Analog	BIAS1 input for LCD.
LCDBIAS2	3			
LCDBIAS2		I	Analog	BIAS2 input for LCD.
LCDBIAS3	78			
LCDBIAS3		I	Analog	BIAS3 input for LCD.
COM0	77			
COM0		O	Analog	COM0 output for LCD.
RE4/COM1	76			
RE4		I/O	ST	Digital I/O.
COM1		O	Analog	COM1 output for LCD.
RE5/COM2	75			
RE5		I/O	ST	Digital I/O.
COM2		O	Analog	COM2 output for LCD.
RE6/COM3	74			
RE6		I/O	ST	Digital I/O.
COM3		O	Analog	COM3 output for LCD.
RE7/CCP2/SEG31	73			
RE7		I/O	ST	Digital I/O.
CCP2(2)		I/O	ST	Capture 2 input/Compare 2 output/PWM2 output.
SEG31		O	Analog	SEG31 output for LCD.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C = ST with I^2C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-3: PIC18F8X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number TQFP	Pin Type	Buffer Type	Description
				PORTG is a bidirectional I/O port.
RG0/SEG30	5			
RG0		I/O	ST	Digital I/O.
SEG30		O	Analog	SEG30 output for LCD.
RG1/TX2/CK2/SEG29	6			
RG1		I/O	ST	Digital I/O.
TX2		O	—	AUSART2 asynchronous transmit.
CK2		I/O	ST	AUSART2 synchronous clock (see related RX2/DT2).
SEG29		O	Analog	SEG29 output for LCD.
RG2/RX2/DT2/SEG28	7			
RG2		I/O	ST	Digital I/O.
RX2		I	ST	AUSART2 asynchronous receive.
DT2		I/O	ST	AUSART2 synchronous data (see related TX2/CK2).
SEG28		O	Analog	SEG28 output for LCD.
RG3/SEG27	8			
RG3		I/O	ST	Digital I/O.
SEG27		O	Analog	SEG27 output for LCD.
RG4/SEG26	10			
RG4		I/O	ST	Digital I/O.
SEG26		O	Analog	SEG26 output for LCD.
RG5				See $\overline{MCLR}$/VPP/RG5 pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C = ST with I^2C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-3: PIC18F8X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTJ is a bidirectional I/O port.
RJ0/SEG32	62			
RJ0		I/O	ST	Digital I/O.
SEG32		O	Analog	SEG32 output for LCD.
RJ1/SEG33	61			
RJ1		I/O	ST	Digital I/O.
SEG33		O	Analog	SEG33 output for LCD.
RJ2/SEG34	60			
RJ2		I/O	ST	Digital I/O.
SEG34		O	Analog	SEG34 output for LCD.
RJ3/SEG35	59			
RJ3		I/O	ST	Digital I/O.
SEG35		O	Analog	SEG35 output for LCD.
RJ4/SEG39	39			
RJ4		I/O	ST	Digital I/O.
SEG39		O	Analog	SEG39 output for LCD.
RJ5/SEG38	40			
RJ5		I/O	ST	Digital I/O
SEG38		O	Analog	SEG38 output for LCD.
RJ6/SEG37	41			
RJ6		I/O	ST	Digital I/O.
SEG37		O	Analog	SEG37 output for LCD.
RJ7/SEG36	42			
RJ7		I/O	ST	Digital I/O.
SEG36		O	Analog	SEG36 output for LCD.
VSS	11, 31, 51, 70	P	—	Ground reference for logic and I/O pins.
VDD	12, 32, 48, 71	P	—	Positive supply for logic and I/O pins.
AVSS	26	P	—	Ground reference for analog modules.
AVDD	25	P	—	Positive supply for analog modules.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C = ST with I^2C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

REGISTER 2-3: ADCON2: A/D CONTROL REGISTER 2

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADFM	—	ACQT2	ACQT1	ACQT0	ADCS2	ADCS1	ADCS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **ADFM:** A/D Result Format Select bit
1 = Right justified
0 = Left justified

bit 6 **Unimplemented:** Read as '0'

bit 5-3 **ACQT<2:0>:** A/D Acquisition Time Select bits
111 = 20 TAD
110 = 16 TAD
101 = 12 TAD
100 = 8 TAD
011 = 6 TAD
010 = 4 TAD
001 = 2 TAD
000 = 0 TAD(1)

bit 2-0 **ADCS<2:0>:** A/D Conversion Clock Select bits
111 = FRC (clock derived from A/D RC oscillator)(1)
110 = FOSC/64
101 = FOSC/16
100 = FOSC/4
011 = FRC (clock derived from A/D RC oscillator)(1)
010 = FOSC/32
001 = FOSC/8
000 = FOSC/2

Note 1: If the A/D FRC clock source is selected, a delay of one TCY (instruction cycle) is added before the A/D clock starts. This allows the SLEEP instruction to be executed before starting a conversion.

The value in the ADRESH:ADRESL registers is unknown following Power-on and Brown-out Resets and is not affected by any other Reset.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine acquisition time, see **Section 2.1 "A/D Acquisition Requirements"**. After this acquisition time has elapsed, the A/D conversion can be started. An acquisition time can be programmed to occur between setting the GO/$\overline{\text{DONE}}$ bit and the actual start of the conversion.

The following steps should be followed to perform an A/D conversion:

1. Configure the A/D module:
   - Configure analog pins, voltage reference and digital I/O (ADCON1)
   - Select A/D input channel (ADCON0)
   - Select A/D acquisition time (ADCON2)
   - Select A/D conversion clock (ADCON2)
   - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
   - Clear ADIF bit
   - Set ADIE bit
   - Set GIE bit
3. Wait the required acquisition time (if required).
4. Start conversion:
   - Set GO/$\overline{\text{DONE}}$ bit (ADCON0<1>)
5. Wait for A/D conversion to complete by either:
   - Polling for the GO/$\overline{\text{DONE}}$ bit to be cleared

   OR
   - Waiting for the A/D interrupt
6. Read A/D Result registers (ADRESH:ADRESL); clear bit, ADIF, if required.
7. For the next conversion, go to Step 1 or Step 2, as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2 TAD is required before the next acquisition starts.

FIGURE 2-2: A/D TRANSFER FUNCTION

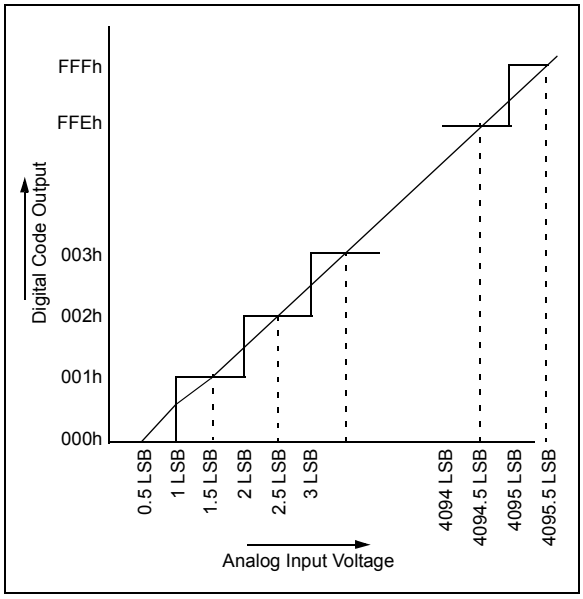
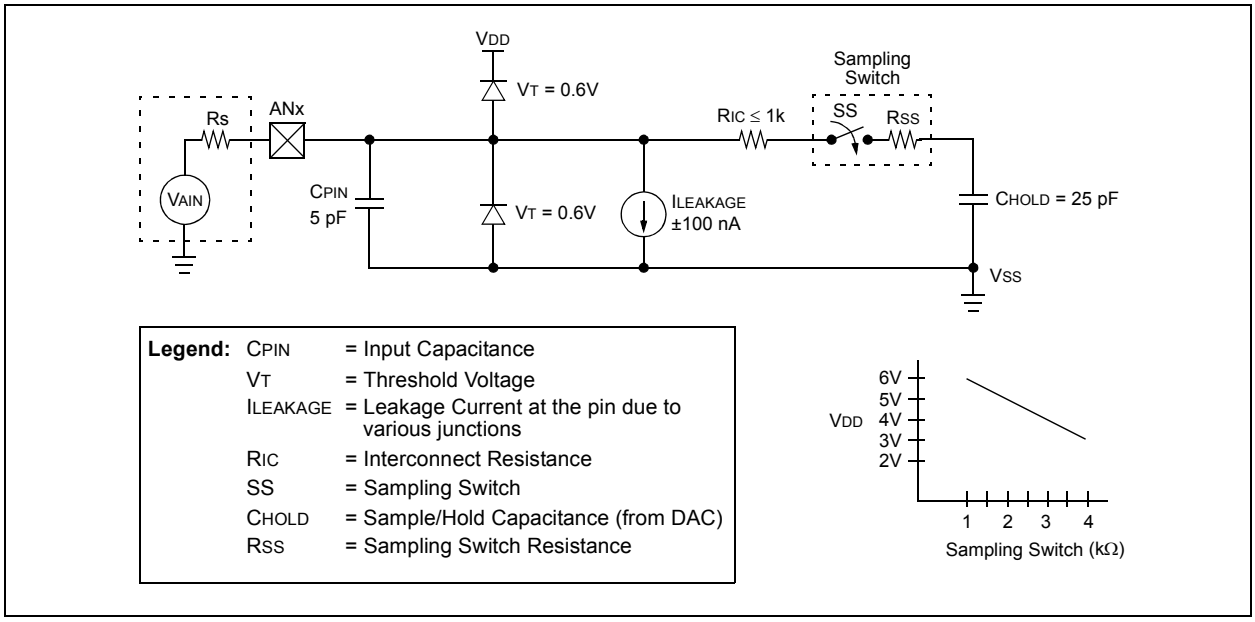


FIGURE 2-3: ANALOG INPUT MODEL



2.8 Use of the ECCP2 Trigger

An A/D conversion can be started by the Special Event Trigger of the ECCP2 module. This requires that the CCP2M<3:0> bits (CCP2CON<3:0>) be programmed as '1011' and that the A/D module is enabled (ADON bit is set). When the trigger occurs, the GO/$\overline{\text{DONE}}$ bit will be set, starting the A/D acquisition and conversion, and the Timer1 (or Timer3) counter will be reset to zero. Timer1 (or Timer3) is reset to automatically repeat the A/D acquisition period with minimal software overhead (moving ADRESH:ADRESL to the desired location). The appropriate analog input channel must be selected and the minimum acquisition period is either timed by the user, or an appropriate TACQ time selected before the Special Event Trigger sets the GO/$\overline{\text{DONE}}$ bit (starts a conversion).

If the A/D module is not enabled (ADON is cleared), the Special Event Trigger will be ignored by the A/D module, but will still reset the Timer1 (or Timer3) counter.

TABLE 2-2: REGISTERS ASSOCIATED WITH A/D OPERATION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	(3)
PIR1	—	ADIF	RC1IF	TX1IF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	(3)
PIE1	—	ADIE	RC1IE	TX1IE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	(3)
IPR1	—	ADIP	RC1IP	TX1IP	SSP1IP	CCP1IP	TMR2IP	TMR1IP	(3)
PIR2	OSCFIF	CMIF	—	—	BCL1IF	HLVDIF	TMR3IF	CCP2IF	(3)
PIE2	OSCFIE	CMIE	—	—	BCL1IE	HLVDIE	TMR3IE	CCP2IE	(3)
IPR2	OSCFIP	CMIP	—	—	BCL1IP	HLVDIP	TMR3IP	CCP2IP	(3)
ADRESH	A/D Result Register High Byte								(3)
ADRESL	A/D Result Register Low Byte								(3)
ADCON0	—	—	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	(3)
ADCON1	—	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	(3)
ADCON2	ADFM	—	ACQT2	ACQT1	ACQT0	ADCS2	ADCS1	ADCS0	(3)
TRISA	TRISA7(1)	TRISA6(1)	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	(3)
TRISF	TRISF7	TRISF6	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	(3)
TRISH(2)	TRISH7	TRISH6	TRISH5	TRISH4	TRISH3	TRISH2	TRISH1	TRISH0	(3)

Legend: — = unimplemented, read as '0'. Shaded cells are not used for A/D conversion.

Note 1: PORTA<7:6> and their direction bits are individually configured as port pins based on various primary oscillator modes. When disabled, these bits read as '0'.

2: These registers are not implemented on 64-pin devices.

3: For these Reset values, see the *"*PIC18F6390/6490/8390/8490 *Data Sheet"* (DS39629).

3.0 SPECIAL FEATURES OF THE CPU

Note:	For additional details on the Configuration bits, refer to **Section 23.1 "Configuration Bits" in** the *"PIC18F6390/6490/8390/8490 Data Sheet"* (DS39629). Device ID information presented in this section is for the PIC18F6393/6493/8393/8493 devices only.

PIC18F6393/6493/8393/8493 devices include several features intended to maximize reliability and minimize cost through elimination of external components. These include:

- Device ID Registers

3.1 Device ID Registers

The Device ID registers are "read-only" registers. They identify the device type and revision to device programmers and can be read by firmware using table reads.

TABLE 3-1: DEVICE IDs

File Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Default/ Unprogrammed Value
3FFFFEh	DEVID1	DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0	xxxx xxxx(1)
3FFFFFh	DEVID2	DEV10	DEV9	DEV8	DEV7	DEV6	DEV5	DEV4	DEV3	xxxx xxxx(1)

Legend: x = unknown

Note 1: See Register 3-1 and Register 3-2 for DEVID values. DEVID registers are read-only and cannot be programmed by the user.

FIGURE 4-1: PIC18F6393/6493/8393/8493 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)

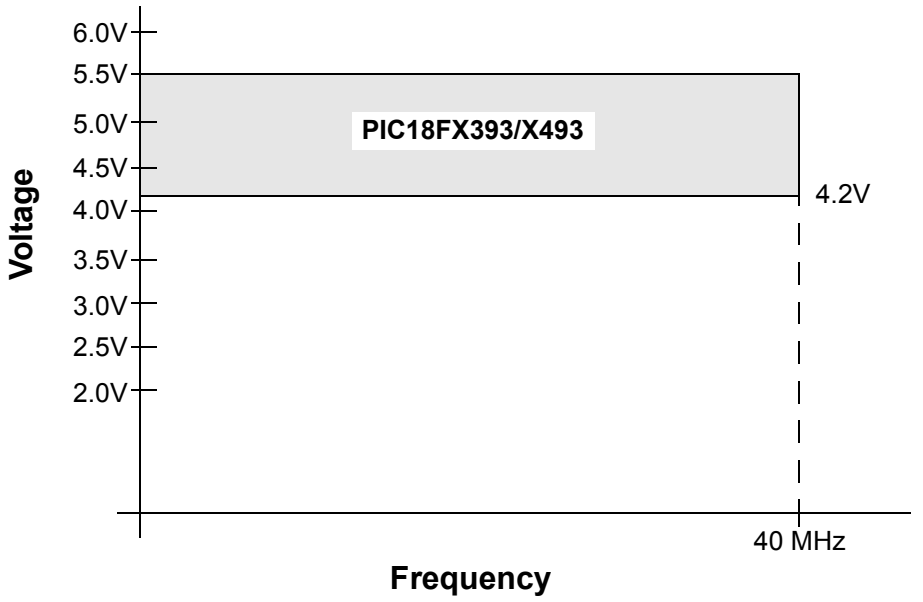
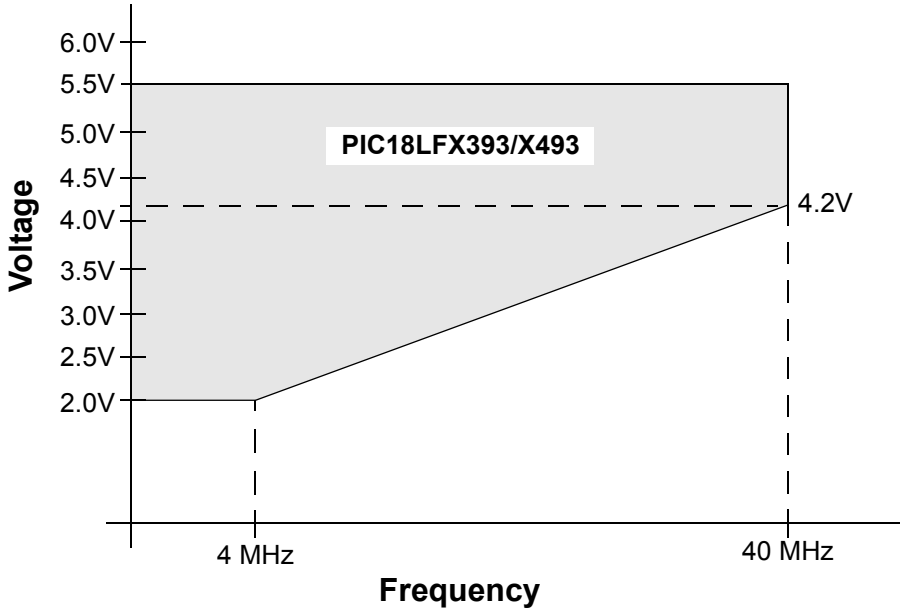


FIGURE 4-2: PIC18LF6393/6493/8393/8493 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



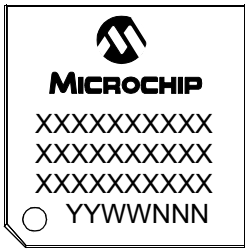
F_{MAX} = (16.36 MHz/V) ($V_{DDAPPMIN}$ – 2.0V) + 4 MHz

Note: $V_{DDAPPMIN}$ is the minimum voltage of the PIC® device in the application.

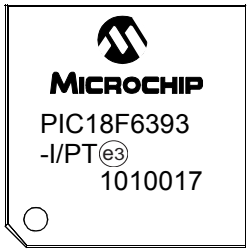
5.0 PACKAGING INFORMATION

5.1 Package Marking Information

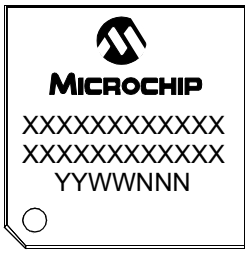
64-Lead TQFP (10x10x1mm)



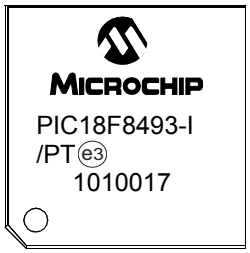
Example



80-Lead TQFP (12x12x1mm)



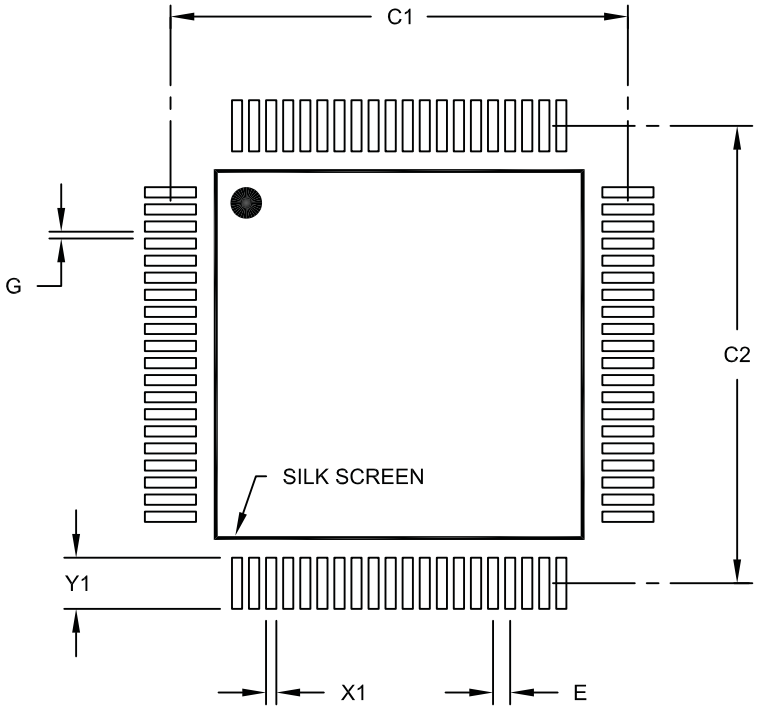
Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
		Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.	

80-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		13.40	
Contact Pad Spacing	C2		13.40	
Contact Pad Width (X80)	X1			0.30
Contact Pad Length (X80)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2092A

NOTES:

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- **General Technical Support** – Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
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- Field Application Engineer (FAE)
- Technical Support
- Development Systems Information Line

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Technical support is available through the web site at: http://support.microchip.com

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	/XX	XXX
Device	Temperature Range	Package	Pattern

Device[1), (2)]	PIC18F6393, PIC18F6493, PIC18F8393, PIC18F8493 – VDD range: 4.2V to 5.5V PIC18LF6393, PIC18LF6493, PIC18LF8393, PIC18LF8493 – VDD range: 2.0V to 5.5V
Temperature Range	I = -40°C to +85°C (Industrial)
Package	PT = TQFP (Thin Quad Flatpack)
Pattern	QTP, SQTP, Code or Special Requirements (blank otherwise)

Examples:

a) PIC18LF6393-I/PT 301 = Industrial temp., TQFP package, Extended VDD limits, QTP pattern #301.

b) PIC18LF6393-I/PT = Industrial temp., TQFP package, Extended VDD limits.

Note 1: F = Standard Voltage Range
LF = Wide Voltage Range
2: T = in Tape and Reel TQFP packages only.